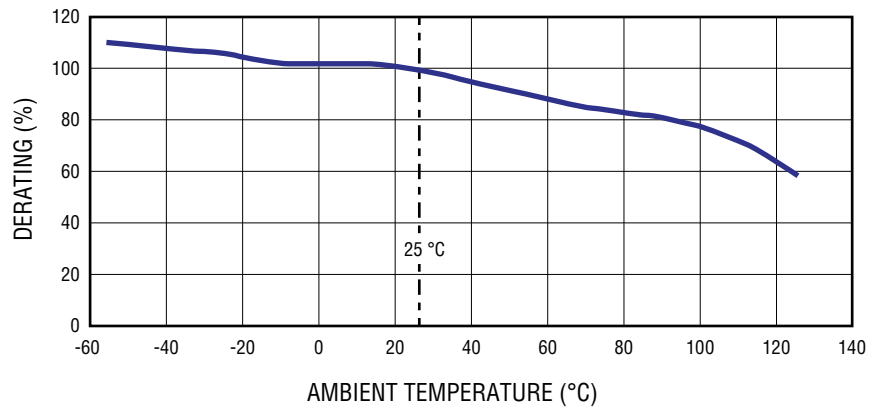


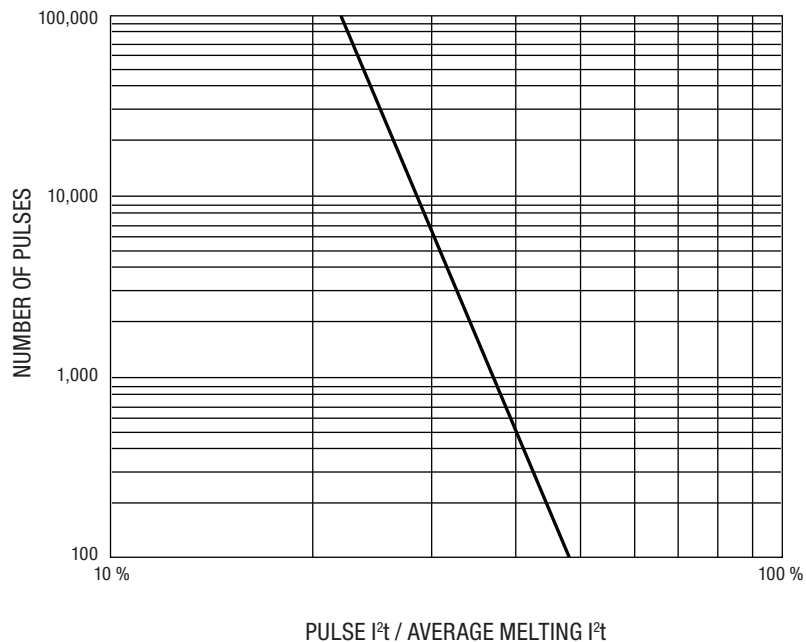
SF-2923HC-C Series – High Current SMD Fuses

BOURNS®

Current Rating Thermal Derating Curve



Pulse Cycle Withstand Capability



Specifications are subject to change without notice.

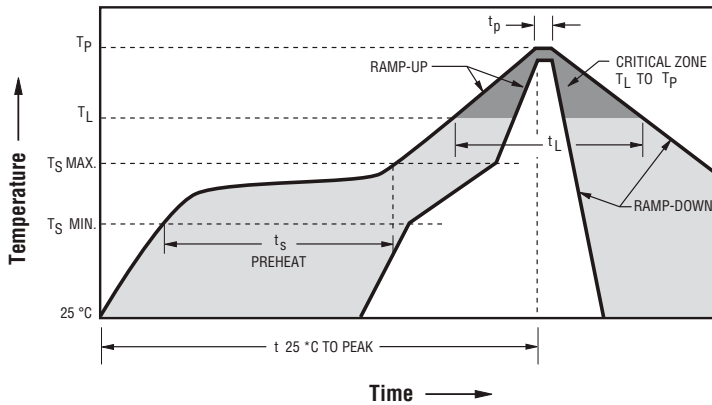
Users should verify actual device performance in their specific applications.

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SF-2923HC-C Series – High Current SMD Fuses

BOURNS®

Solder Reflow Recommendations



Profile Feature	Pb-Free Assembly
Preheat / Soak:	
Temperature Min. (T_{smin})	150 °C
Temperature Max. (T_{smax})	200 °C
Time (t_s) from (T_{smin} to T_{smax})	60~180 seconds
Ramp Up Rate (T_L to T_P)	3 °C / second max.
Ramp Up Rate (T_{smax} to T_L)	5 °C / second max.
Liquidous Temperature (T_L)	217 °C
Time (t_L) maintained above T_L	60~90 seconds
Peak Package Body Temperature (T_P)	235 °C $\pm$ 5 °C
Time within 5 °C of actual peak temperature (T_P)	20~30 seconds*
Ramp Down Rate (T_P to T_L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.
Do not exceed	240 °C

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

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